

# G-None PAD

Elastomeric material, created in mimircry of nature (Geko). G-None pads can be used for wafer, mask, and glass handling, up to 300°C. Your end-effector will be able to handle even warped wafers, till 5 mm. In addition, there are no limits from your current blades design as G-None pads have always customized shapes and dimensions for you tool.



## Features

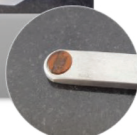
- Enhance tool handling performance - Reduce wafer-slip
  - Prevent wafer misalignment
- Increased throughput
  - Robot speed up for 2-6 times
- Hardware utilities reduction
  - Reduce costs for air/vacuum supply
- Chemical Resistance: IPA, Acetone Corossive Gasses (CF<sub>4</sub> + O<sub>2</sub>, BCl<sub>3</sub> + Cl<sub>2</sub>, NF<sub>3</sub>, SF<sub>6</sub>, C<sub>2</sub>F<sub>6</sub>)
- High temperature substrate handling up to 300°C
- Contamination free / Zero Particles Generation
- No-holding mark
- Easy and simple cleaning



Mimicry of nature to get the slip resistance function



Etch process  
(8")



Etch process  
(12")



CVD process  
(12")



Diffusion and Etch  
process  
(8" and 12")

